Thermal Conductivity Testing Report

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OBJECTIVE

The objective is to determine the thermal conductivity of the provided thermal paint samples at ambient temperature.

APPARATUS



As detailed in Appendix 1, a C-Therm TCi Thermal Conductivity Analyzer (above) was used in this study to perform all the thermal conductivity and thermal effusivity measurements. The C-Therm TCi Thermal Conductivity Analyzer is a modular system with a range of sensors available to accommodate a diverse range of samples. When operated with a Modified Transient Plane Source sensor (left), it is an integrated solution for thermal conductivity and thermal effusivity measurement and operates in compliance with ASTM Standard D7984-16. When operated with the Transient Line Source sensor (right), it operates in compliance with applicable international standards for the testing of polymer melts, soils, soft rock and unconsolidated solids, including ASTM Standard D5334, ASTM Standard D5930, and IEEE Standard 442-1981.

In the case of these samples, the C-Therm TCi Thermal Conductivity Analyzer was used in the Modified Transient Plane Source (MTPS) configuration, which is suited to the analysis of solids, liquids, powders, pastes, textiles, and similar materials. The system was operated in accordance with ASTM D7984. The aerogels calibration was employed for sample testing. In accordance with established test procedures for aerogels, no contact agent was employed and a 3 second test was used. Density (measured via a volumetric-gravimetric method) and specific heat (obtained from literature for Isonem paint) were input to the data analysis algorithm to ensure maximum accuracy of the aerogels test method.



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SAMPLES

Sample provided by the client are pictured below:





Sample were used as provided; two layers were required for Thermal Paint 3cm and 2cm samples in order to prevent the sensor heat pulse from reaching the far end of the material. The final sample, Isonem Thermal Paint (not pictured) was shipped with insufficient thickness for accurate testing. This paint will be tested after appropriate sample machining and the final report shall be issued.

RESULTS

The results for samples are summarized in Table 1 and graphically in Figure 1. Note: RSD is relative standard deviation and k is thermal conductivity in W/mK

Sample	Thermal Paint 2cm		Thermal Paint 3cm	
Test	k (W/mK)	RSD (N=5)	k (W/mK)	RSD (N=5)
1	0.039	0.6%	0.039	1.0%
2	0.039	0.9%	0.040	0.5%
3	0.040	1.6%	0.040	1.1%
Average	0.039	1.5%	0.039	1.6%



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	Thermal		Thermal	
Sample	Paint 5cm		Paint Uncut	
Test	k (W/mK)	RSD (N=5)	k (W/mK)	RSD (N=5)
1	0.031	2.7%	0.033	1.2%
2	0.032	0.5%	0.034	0.5%
3	0.033	1.2%	0.033	1.2%
Average	0.032	2.8%	0.033	1.4%

Table 2. Thermal conductivity test results of 5cm and uncut samples.



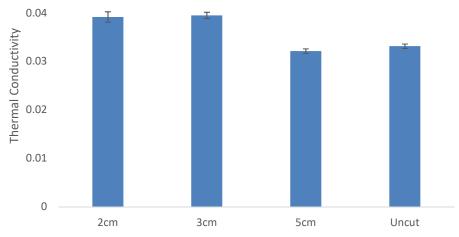


Figure 1: Graphical Comparison of the Samples' Thermal Conductivity

CONCLUSION

The thermal conductivity of the samples provided were characterized using the modified transient plane source (MTPS) method. The Thermal Paint 3cm sample has the highest thermal conductivity. The 5cm and Uncut samples had lower thermal conductivity.



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APPENDIX 1 – C-Therm TCi Thermal Conductivity Analyzer

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Appendix 1-1

SIMPLIFYING Thermal Conductivity (k)

FAST, ACCURATE TESTING 0 to 500 W/mK in seconds

WIDE TEMPERATURE RANGE

-50 °C to 200 °C With option to extend to 500 °C

NO SAMPLE PREPARATION Unlimited sample size

NON-DESTRUCTIVE Leaves sample unaltered

EASY-TO-USE No user-calibration required

HIGHLY VERSATILE Tests solids, liquids, powders and pastes

MODULAR Configurable to meet a range of needs and budget. Option to pair with C-Therm Dilatometer.





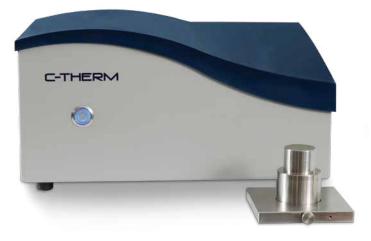
ALSO PROVIDES: EFFUSIVITY | DIFFUSIVITY | HEAT CAPACITY | DENSITY

SIMPLIFYING THERMAL CONDUCTIVITY

C-Therm's patented sensor technology makes thermal conductivity simpler and more accessible to measure. There is simply no faster or easier way to measure thermal conductivity and effusivity.

With the C-Therm TCi there is no complex regression analysis necessary as with other transient methods. No special sample preparation is required and there is no need to measure additional sample material properties such as heat capacity.

The TCi is provided with one versatile sensor for testing all types of materials; including solids, liquids, powders and pastes. A second sensor can be added for increased capacity.



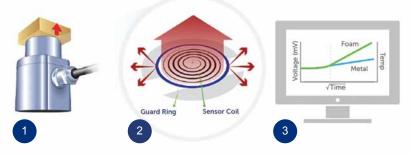
The testing procedure is noninvasive; samples remain unaltered and reusable. The system offers users exceptional versatility in being able to operate in a variety of environments, including thermal chambers, high pressure vessels and glove boxes. Fast and accurate testing made easy!

Principles of Operation

The C-Therm TCi employs the patented Modified Transient Plane Source (MTPS) technique. The one-sided, interfacial heat reflectance sensor applies a momentary constant heat source to the sample. Thermal conductivity and effusivity are measured directly, providing a detailed overview of the thermal characteristics of the sample.



How It Works



The TCi is factory-calibrated for directly measuring both thermal conductivity (k) & thermal effusivity:



Effusivity = $\sqrt{k\rho c_{\mu}}$

Thermal Conductivity

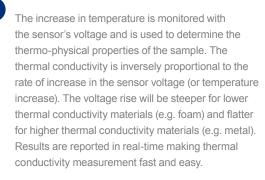
sivity = $\sqrt{k\rho c_{\rho}}$

 $k = thermal \ conductivity \ (W/m \cdot K)$

- $\rho = density (kg/m^3)$
- c, = heat capacity (J/kg K)

A known current is applied to the sensor's spiral heating element, providing a small amount of heat.

The sensor's guard ring is fired simultaneously supporting a one-dimensional heat exchange between the primary sensor coil and the sample. The current applied to the coil results in a rise in temperature at the interface between the sensor and sample, which induces a change in the voltage drop of the sensor element.



VERSATILE

EASILY TEST SOLIDS, LIQUIDS, POWDERS AND PASTES

APPLICATIONS



Thermal Interface Materials



Explosives



Textiles







Rubber and Polymers







Oil & Gas



Metal Hydrides







Batteries

Geological



Thin Films



Nanomaterials



Insulation



Nuclear



LED Lighting







Solids: Conductive Polymers

C-Therm has provided a breakthrough in the characterization of critical performance attributes of conductive polymers used in electronics and automotive industries. The main advantage the technique offers is the flexibility to test a wide range of sample geometries. As an example, clients at a large polymer producer use the test samples from their tensile testing regimen to also test the in-plane and through-plane thermal conductivity with the C-Therm TCi. There is no longer the need to destructively machine or form specific sample sizes/dimensions to test thermal conductivity!

Powders: From Explosives to Ink Toners

The C-Therm TCi is being used to safely test the stability, degradation, and shelf life of explosives because it is the only instrument engineered for evaluating the thermal conductivity of powders safely. Sample volumes are as small as 1.25 ml. This is also critical to a rapidly growing client base in metal hydrides, where materials are expensive and available in low quantities. The technology is also migratable to manufacturing environments as a cost-effective way to monitor powder processes for moisture and homogeneity.

Pastes: Keeping the Hottest Electronics Cool

The faster and smaller microprocessors become, the more heat they generate. C-Therm's TCi is providing vital insights into the development of all materials that contribute to the overall thermal budget, including thermal interface materials such as thermal grease and gap pads. These materials are typically compressible and the thermal conductivity varies with changes in the densification of the material. Clients use the C-Therm Compression Test Accessory (CTA) to precisely control the compaction of the sample in producing results reflective of the actual application conditions for the material.

Liquids: Under Pressure

The C-Therm TCi is helping manufacturers improve the heat transfer properties of liquids. C-Therm is unique in offering the capability to accurately measure the thermal conductivity of liquids; the short test time (<1 second) and small sample volume requirements negate the convective errors typical in liquid testing with traditional techniques. As an example, clients in the Oil & Gas field use C-Therm's High Pressure Cell (HPC) accessory in measuring the impact of elevated atmospheric conditions and temperature on the thermal conductivity of fluids.

COMPARISON

FASTER, EASIER, MORE VERSATILE

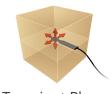


C-Therm TCi (Modified Transient Plane Source)

\$



Guarded Hot Plate



Transient Plane Source

\$\$



\$\$\$

SPEED	& FLEXIBILITY	
Sampla	Droporation	

Sample Preparation	None Required	Extensive	Some	Extensive
Testing Time	Seconds	Hours	Minutes	Hours*
Training Time	Minimal	Moderate	Significant**	Extensive
Non-Destructive	Yes	No	No	No
Method Development	8	8	•	8

RANGE				
k-Range (W/mK)	0 – 500	0 – 2	0 - 100 (100 - 500 requires C _p)	0 – 500 (requires density & C _P)
Temperature Range (°C)	-50 ℃ to 200 ℃ With option to extend to 500 ℃	-100 °C to 1400 °C	-100 °C to 700 °C	-150 °C to 2800 °C
SAMPLE CONFIGURATION				
Minimum	0.67" diameter (17 mm)	6" x 6" (150 x 150 mm)	Two Identical Samples 1" x 1" (25 x 25 mm)	0.5" diameter (12.4 mm) 0.004" thick (1 mm)
Maximum	Unlimited	24" x 24" (600 x 600 mm)	Two Identical Samples Unlimited	0.5" diameter (12.4 mm) 0.004" thick (1 mm)
Material Testing Capabilities	Solids, Liquids, Powders, Pastes	Solids	Solids, Liquids	Solids

1 Based on publicly available information and feedback from users.

PRICING

* Calculation of thermal conductivity from Laser Flash Diffusivity Measurement requires the additional following material properties: heat capacity (C_p) density, and coefficient of thermal expansion. ** Traditional Transient Plane Source requires iterative testing to obtain the correct experimental parameters in terms of power flux, test time, and sizing of sensor necessary to obtain accurate results.

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MODULAR SCALABLE SOLUTIONS

ACCESSORIES



Compression Test Accessory (CTA)

Compression of sample material increases the density and impacts the effective thermal conductivity of the material. It is important that the level of compaction is controlled and representative of the application conditions of the material. C-Therm's Compression Test Accessory

(CTA) enables researchers testing such materials to precisely control the densification in providing highly reproducible results that better reflect the effective thermal conductivity. The CTA is particularly recommended to users testing textiles/fabrics, insulation batting, thermal interface materials, and powders.



Tenney Jr. Thermal Chamber

The TPS Tenney Jr. Thermal Chamber is recommended to users who wish to measure the thermal conductivity at non-ambient temperatures, from -50 °C to 200 °C. C-Therm's TCi software

enables direct control of the thermal chamber, bypassing manual operation and allowing users to pre-program their desired temperature profile and walk away!



Small-Volume Test Kit (SVTK)

The Small-Volume Test Kit was originally developed with the US Navy Surface Warfare Division specifically for testing energetic materials. The effectiveness of the accessory in reducing convection effect on testing samples make

it ideal for characterizing the thermal conductivity of liquid samples. The SVTK is commonly applied in testing nano and heat transfer fluids, as well as emulsions.



High Pressure Cell (HPC)

C-Therm offers a range of high pressure cells to safely characterize the thermal conductivity of samples under elevated pressure environments up to 2000 PSI (~138 bar). C-Therm's HPCs are popular with researchers in the Oil & Gas, Nuclear and Fuel Cell industries.

DILATOMETRY MODULE

Dilatometry provides key expansion and shrinkage properties of materials under defined temperatures.

TEMPERATURE RANGE	Room Temperature to 1600 °C
TEMP. RESOLUTION	0.1 °C
MAX DISPLACEMENT	4 mm
△I RESOLUTION	1.25 nm/digit
ATMOSPHERE	Air, Vacuum, Inert Gas
SAMPLE DIMENSIONS	10 to 50 mm long x max ϕ 12 mm
SAMPLE HOLDER	Fused Silica, Alumina
CONFIGURATIONS	Single or Dual Rod LVDT System 1200 °C or 1600 °C furnace
HEATING ELEMENT	FeCrAl, SiC
RATE OF INCREASE (°C)	1 °C/min up to 50 °C/min



C-Therm's latest generation TCi offers an innovative new option to pair the controller with an optional dilatometer. This offers researchers significant savings in leveraging commonalities of the TCi control electronics while expanding the platform's capabilities to dilatometry.

THERMAL EXPANSION • FIRING • PHASE TRANSITION SHRINKAGE • SINTERING

Conforms to all major standard methods for dilatometry, including ASTM E228.

PROVEN

For over a decade, C-Therm's innovative sensor technology has been pioneering the way for many of the world's most prominent manufacturers, research facilities, and academic institutions to test and measure thermal properties of materials.

The technology behind the C-Therm TCi represents a paradigm shift in thermal conductivity measurement and earned the inventor behind the technology the Manning Innovation Principle Award and an R&D 100 Award. These coveted awards are given to the top global innovators, and place C-Therm in the distinguished company of such other winners as the developers of the ATM. Polaroid[™] and anti-lock brakes.



C-THERM TCI SPECIFICATIONS

Thermal Conductivity Range	0 to 500 W/mK
Test Time	0.8 to 3 seconds
Minimum Sample Testing Size	17 mm diameter
Maximum Sample Testing Size	Unlimited
Test Method	Modified Transient Plane Source (MTPS)
Minimum Thickness	Nominally 0.5 mm, dependent on thermal
	conductivity of material
Maximum Thickness	Unlimited
Temperature Range	-50 °C to 200 °C
	With option to extend to 500 °C
Precision	Typically better than 1%
Accuracy	Better than 5%
Extra Hook-Ups Required	None
Software	Intuitive Windows®-based software interface. Easy
	export to Microsoft Excel®. Additional functionality
	offers indirect, user-input capabilities for a number
	of other thermo-physical properties including:
	Thermal Diffusivity
	Heat Capacity
	• Density
Input Power	110-230 VAC 50-60 Hz
Certifications	FCC, CE, CSA

For more information, contact:



North America: 1-877-827-7623 International: 1-506-457-1515 info@ctherm.com | www.ctherm.com

COMPANIES AND **ORGANIZATIONS USING C-THERM'S** PATENTED **TECHNOLOGY:**

NASA

University of California Averv Philip Morris Astra Zeneca **US** Navy Patheon Universidade de Aveiro Raytheon Corning Engelhard Universidade Federal de Santa Caterina Wyeth Stowe Woodward INSA **Dow Corning** Exxon Mobil Hewlett Packard NRC Liberec University National University of Singapore Petrobas Henkel Nanocomposix

Canadian Explosives Research Lab







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APPENDIX 2 – Reference Material Test Results

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Reference Material Results

An accuracy check was performed on the instrument prior to running any tests on the standard reference materials of the calibrations to be used and confirmed the instrument was performing well within the stated accuracy specification of 5%. The accuracy of the measurements conducted under specific environmental conditions can be examined by measuring reference materials with externally certified thermal conductivity values. In comparing the observed measurements of the measurements for unknown thermal conductivity values of the materials, the accuracy of the measurements for unknown samples can be evaluated. The results for the reference accuracy check for the measurements carried out in this study are listed in the table below.

Table A1 – Reference Material Test

Reference Material	Measured Thermal Conductivity (W/m·K)	Avg. of the Measured Thermal Conductivity	RSD (%)	Expected Thermal Conductivity (W/m·K)	Bias (%)
	0.062	0.062	0.2	0.0609	1.2
LAF6720	0.062				
	0.062				
	0.061				
	0.062				